



EXPEDITED PROCEDURE - EXAMINING GROUP 2827

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Applicant: Kie Y. Ahn et al. Examiner: James M. Mitchell  
Serial No.: 09/817,447 Group Art Unit: 282  
Filed: March 26, 2001 Docket: 303.459US2  
Title: METHODS FOR MAKING COPPER AND OTHER METAL  
INTERCONNECTIONS IN INTEGRATED CIRCUITS

AMENDMENT & RESPONSE UNDER 37 C.F.R. § 1.116

Box AF  
Commissioner for Patents  
Washington, D.C. 20231

In response to the final Office Action mailed May 6, 2002, please amend the application as follows:

IN THE CLAIMS

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect amendment of previously pending claims 46 and 52. The specific amendments to individual claims are detailed in the following marked up set of claims.

46. (Amended) An integrated-circuit assembly comprising:  
an insulative layer having opposing first and second major surface, with the first major surface having a trench or hole, the trench or hole having an edge;  
a first diffusion barrier having an in-portion lining the trench or hole and having an out-portion outside the trench or hole and on the first major surface, with the out-portion having an edge adjacent the edge of the trench or hole;  
a second diffusion barrier on the out-portion of the first diffusion barrier [insulative layer] and having an edge substantially flush with a least a portion of the edge of the [trench or hole] first diffusion barrier, with the second diffusion barrier comprising a zinc oxide material;